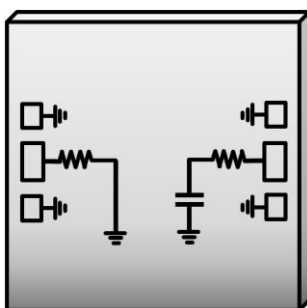


## Typical Applications

- Communication Systems
- Point to Point Radio
- Fiber Optics
- Test Equipment
- Wideband Military & Space

## Features

- Broadband 50-Ohm Termination
- AC and DC coupled RF Port Options
- Return Loss: 19.7dB @ 25GHz
- Die Size: 1.00 x 0.75 x 0.1 mm; Matches AGATNxx, AGLPFxxx, AGBPFxxx, and AGBSFxxx series MMICs

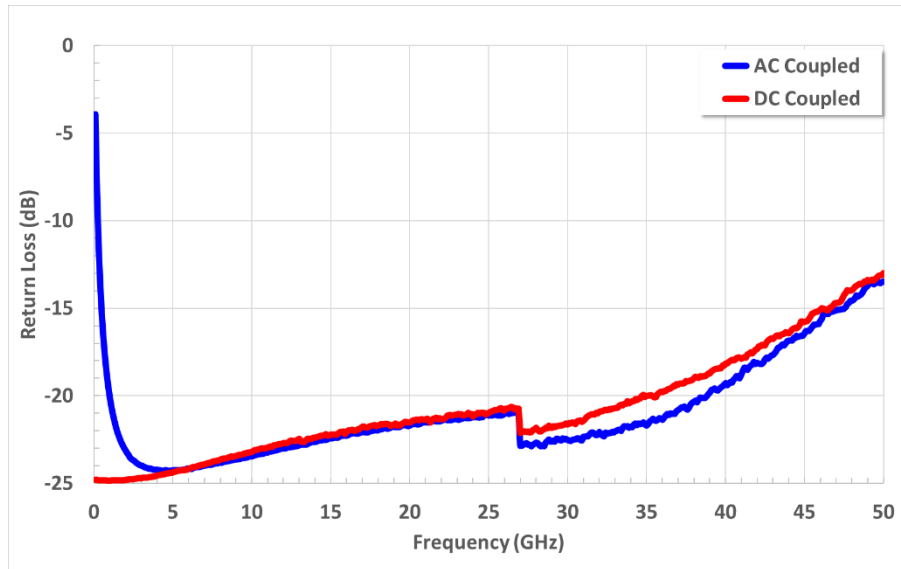


## Electrical Specifications (TA = +25°C)

Parameter	Units	Minimum	Typical	Maximum
Frequency (DC Coupled) (AC Coupled)	GHz	DC 0.25		50.0 50.0
Return Loss	dB	12	18	23
Package Type			Die	

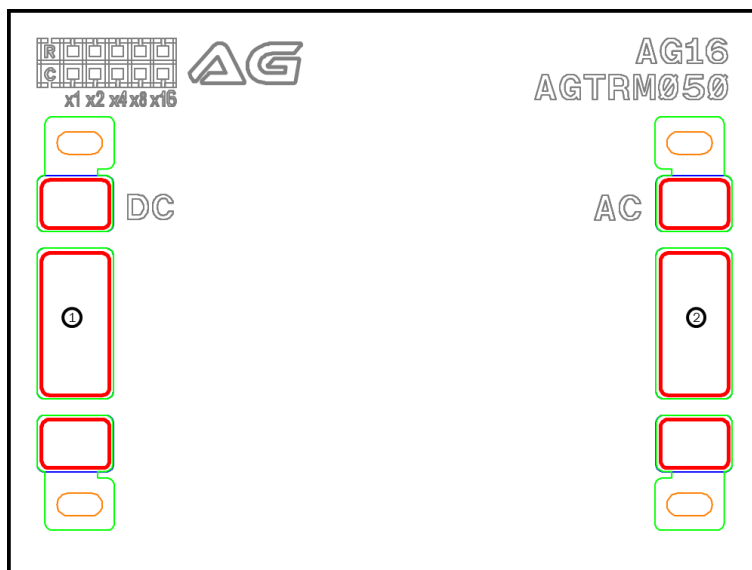
## Performance Graphs

### Return Loss (Simulated)



AGTRM050 Datasheet v01	Information on this datasheet is believed to be accurate and reliable. Specifications are subject to change without notice	For price, delivery, and place to order contact: AmpliTech Sales 155 Plant Avenue, Hauppauge, NY 11788 USA Tel. +1 631.521.7831 Order online at <a href="http://www.AmpliTechInc.com">www.AmpliTechInc.com</a>	Pg.2
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## Outline Drawing (DXF outline available)



## Pad Descriptions

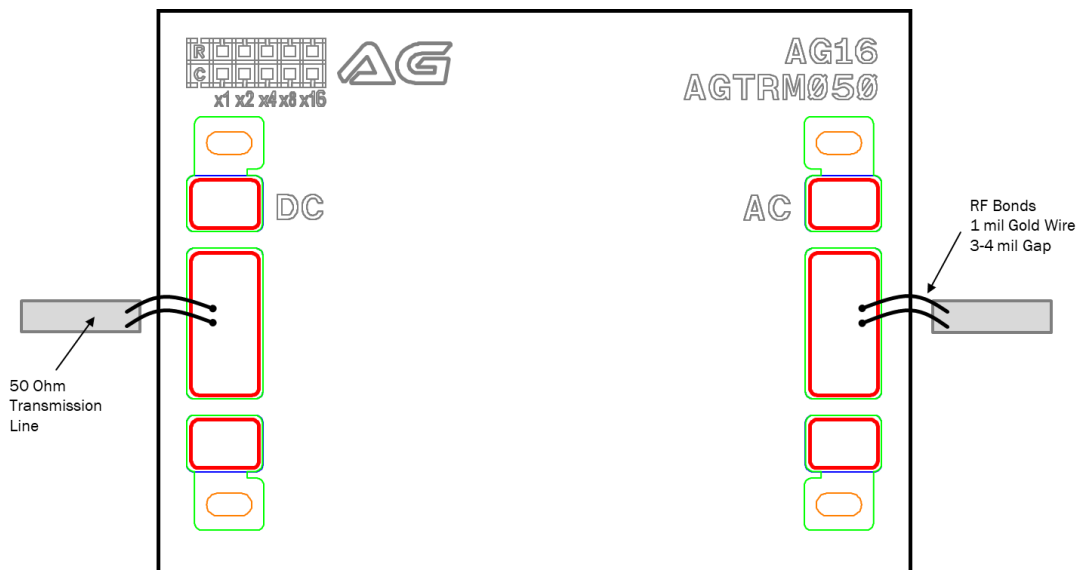
Pad	Function	Pad Size	Description
1	RFIN_DC	101x200μm	DC coupled 50Ω Matched
2	RFIN_AC	101x200μm	AC coupled 50Ω Matched
Die Bottom	GND	Backside	Epoxy/Solder to Baseplate

## Absolute Maximum Ratings

Parameter	Rating
Drain Bias Voltage (VDD)	No Bias
RF Input Power (RFIN)	+20dBm*
Channel Temperature	150°C
Storage Temperature	-65 to 150°C
Operating Temperature	-55 to 85°C

\*To be tested

## Assembly Diagrams



## Assembly Notes:

1. Die Thickness is 100μm
2. Bondpad metallization: 7μm gold
3. Backside metallization: 4.5μm gold
4. Silver Epoxy or AuSn Eutectic attach MMIC



## Die Packaging Information

- GP-4 (Gel-Pak)